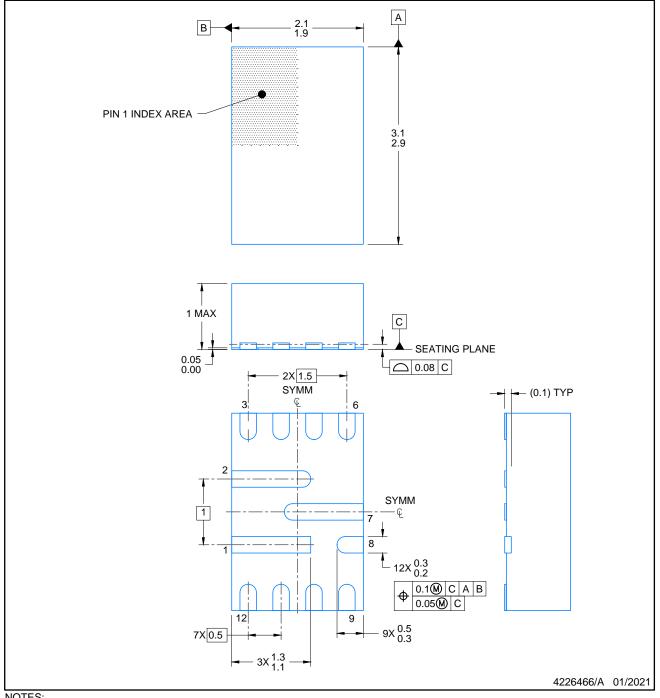
### **RJN0012A**

# **PACKAGE OUTLINE**

### VQFN-HR - 1 mm max height

PLASTIC SMALL OUTLINE- NO LEAD



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.

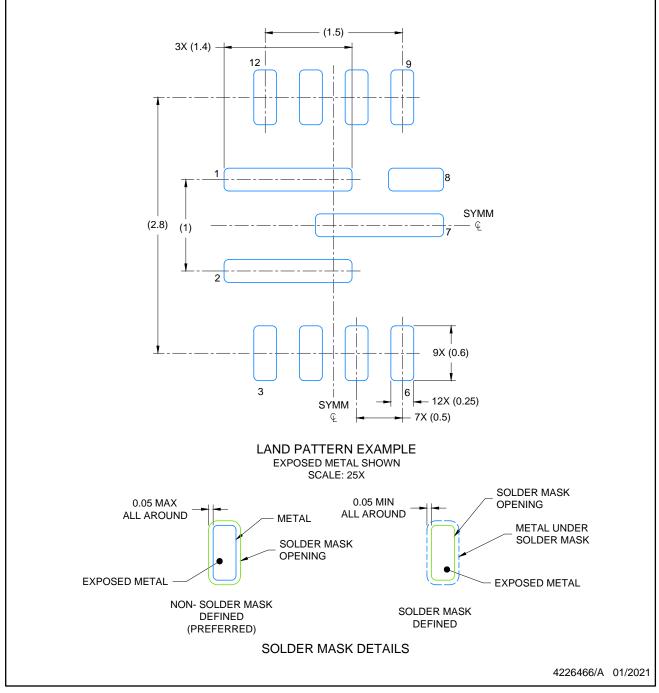


# **RJN0012A**

### **EXAMPLE BOARD LAYOUT**

### VQFN-HR - 1 mm max height

PLASTIC SMALL OUTLINE- NO LEAD



NOTES: (continued)

- 3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271) .
- 4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

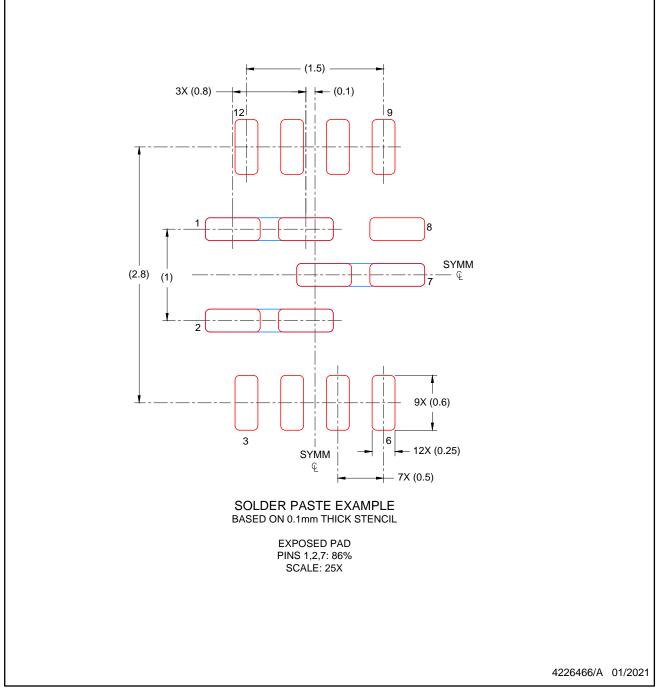


### **RJN0012A**

### **EXAMPLE STENCIL DESIGN**

#### VQFN-HR - 1 mm max height

PLASTIC SMALL OUTLINE- NO LEAD



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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